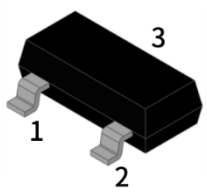
ESDSOT36CLDT1

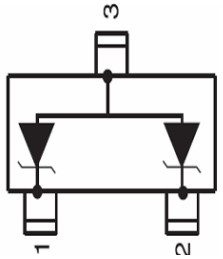
Dual Transient Voltage Suppressors for ESD Protection

1. FEATURES

- The material of product compliance with RoHS requirements and Halogen Free.
- 2 Unidirectional Transil functions.
- Low Leakage.
- Fast Response Time< 1 ns
- Protects I/O Port



SOT23 (TO-236)



2. Mechanical Data

- SOT-23 Small Outline Plastic Package.
- Tin plated leads, solderable per J-STD-002 and JESD22-B102.

3. ORDERING INFORMATION

Device	Min Pack	Inner Box	Outer Carton	Reel
ESDSOT36CLDT1	3000	45000	180000	7 inch

4. MAXIMUM RATINGS (Ta = 25°C)

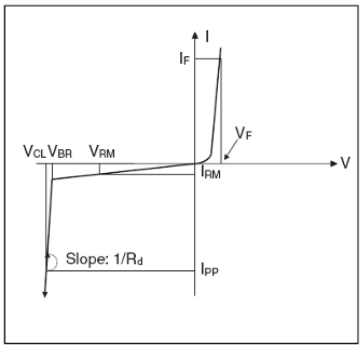
Parameter	Symbol	Limit	Unit
Peak Pulse Power (tp = 8/20μs)	Ppp	240	W
JESD22-A114-B ESD Voltage Per Human Body Model	VESD	±15	V
IEC61000-4-2 Air Model		±30	
IEC61000-4-2 Contact Model		±30	

5. THERMAL CHARACTERISTICS

Storage Temperature Range	TSTG	-55-150	℃
Maximum junction temperature	TJ	150	℃
Operating Temperature Range	Top	-40-125	℃
Maximum lead temperature for soldering during 10s	TL	260	℃

6. ELECTRICAL CHARACTERISTICS (Ta= 25°C unless otherwise specified

Symbol	Parameter
VRM	Stand-off voltage
VBR	Breakdown voltage
VCL	Clamping voltage
IRM	Leakage current
Ipp	Peak pulse current
αT	Voltage temperature coefficient
VF	Forward voltage drop
C	Capacitance
Rd	Dynamic resistance



Part Numbers	Marking	Rated Stand-off Voltage	Maximum Leakage Current	Minimum Breakdown Voltage	Maximum Clamping Voltage		Maximum Pulse Peak Current	Maximum Capacitance
			@ VRM	1mA	1A1)	3A1)	tp=8/20us	0v, 1MHz
		VRM	IRM	VBR	VCL		IPPM	C
		V	μA	V	V	V	A	pF
ESDS0T36CLDT1	36C	36	1	40	60	80	3	30
1). 8/20 waveform used. (see fig2.)								

7.ELECTRICAL CHARACTERISTICS CURVES

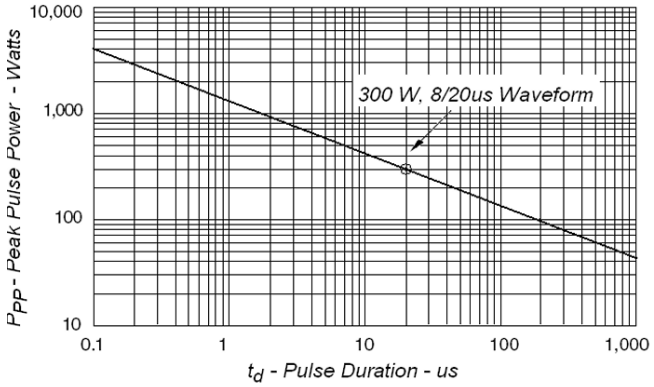


Fig1. Peak Pulse Power VS Pulse Time

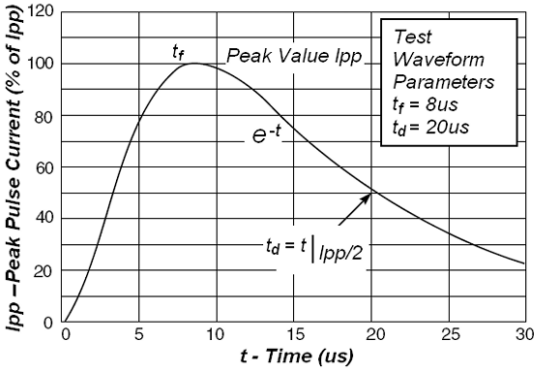


Fig2. Pulse Waveform

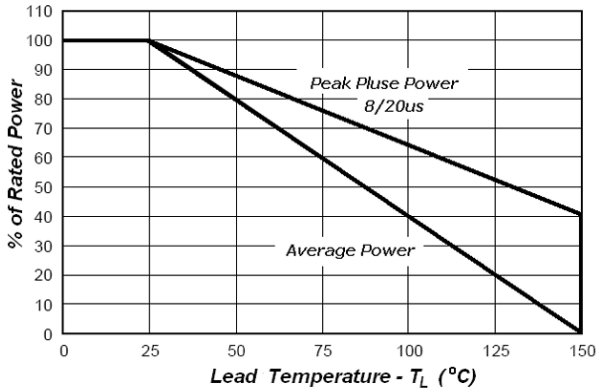
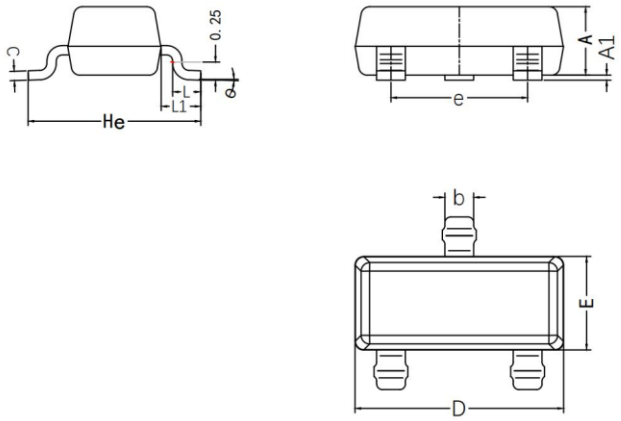


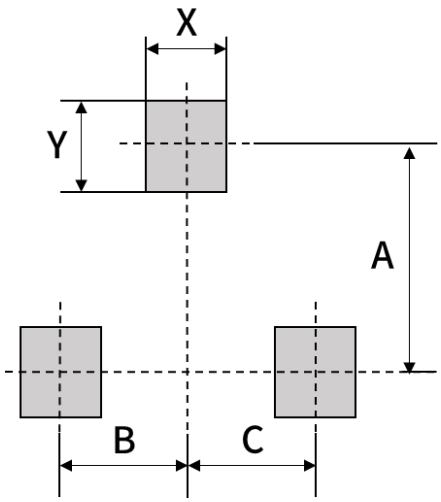
Fig3.Power Derating

8. OUTLINE AND DIMENSIONS



DIM	MIN	NOR	MAX
A	0.85	0.95	1.05
A1	0.01	0.06	0.10
b	0.36	0.44	0.52
c	0.09	0.13	0.18
D	2.80	2.90	3.10
E	1.20	1.30	1.40
e	1.78	1.90	2.04
L	0.30	0.40	0.50
L1	0.35	0.50	0.65
He	2.10	2.35	2.50
θ	0°	–	10°
All Dimensions in mm			

9. SUGGESTED PAD LAYOUT



SOT23		
DIM	mm	inch
A	2.00	0.079
B	0.95	0.037
C	0.95	0.037
X	0.80	0.031
Y	0.90	0.035

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